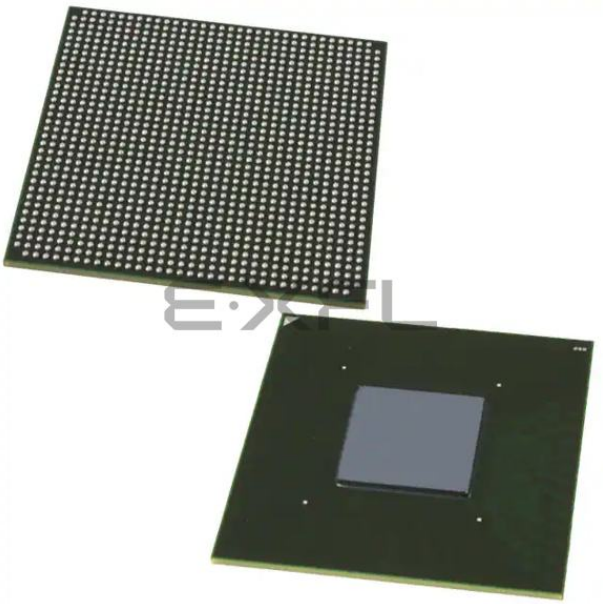

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	362000
Total RAM Bits	19822592
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.12V ~ 1.18V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfb3h4f35i3n

Symbol	Description	Condition	Minimum(1)	Typical	Maximum(1)	Unit
V_{CCIO}	I/O buffers power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
		1.5 V	1.425	1.5	1.575	V
		1.35 V	1.283	1.35	1.418	V
		1.25 V	1.19	1.25	1.31	V
		1.2 V	1.14	1.2	1.26	V
V_{CCD_FPLL}	PLL digital voltage regulator power supply	—	1.425	1.5	1.575	V
V_{CCA_FPLL}	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V_I	DC input voltage	—	–0.5	—	3.6	V
V_O	Output voltage	—	0	—	V_{CCIO}	V
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	–40	—	100	°C
t_{RAMP}(4)	Power supply ramp time	Standard POR	200 µs	—	100 ms	—
		Fast POR	200 µs	—	4 ms	—

(1) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

(4) This is also applicable to HPS power supply. For HPS power supply, refer to t_{RAMP} specifications for standard POR when `HPS_PORSEL` = 0 and t_{RAMP} specifications for fast POR when `HPS_PORSEL` = 1.

Transceiver Specifications for Arria V GT and ST Devices

Table 1-26: Reference Clock Specifications for Arria V GT and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
Supported I/O standards	1.2 V PCML, 1.4 VPCML, 1.5 V PCML, 2.5 V PCML, Differential LVPECL(40), HCSL, and LVDS				
Input frequency from REFCLK input pins	—	27	—	710	MHz
Rise time	Measure at ±60 mV of differential signal(41)	—	—	400	ps
Fall time	Measure at ±60 mV of differential signal(41)	—	—	400	ps
Duty cycle	—	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	300(42)/2000	mV
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to –0.5%	—	—
On-chip termination resistors	—	—	100	—	Ω
V_{ICM} (AC coupled)	—	—	1.2	—	V
V_{ICM} (DC coupled)	HCSL I/O standard for the PCIe reference clock	250	—	550	mV

(40) Differential LVPECL signal levels must comply to the minimum and maximum peak-to-peak differential input voltage specified in this table.
(41) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
(42) The maximum peak-to peak differential input voltage of 300 mV is allowed for DC coupled link.

Quartus Prime 1st Post Tap Pre-Emphasis Setting	Quartus Prime V_{OD} Setting							Unit
	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	
16	—	—	9.56	7.73	6.49	—	—	dB
17	—	—	10.43	8.39	7.02	—	—	dB
18	—	—	11.23	9.03	7.52	—	—	dB
19	—	—	12.18	9.7	8.02	—	—	dB
20	—	—	13.17	10.34	8.59	—	—	dB
21	—	—	14.2	11.1	—	—	—	dB
22	—	—	15.38	11.87	—	—	—	dB
23	—	—	—	12.67	—	—	—	dB
24	—	—	—	13.48	—	—	—	dB
25	—	—	—	14.37	—	—	—	dB
26	—	—	—	—	—	—	—	dB
27	—	—	—	—	—	—	—	dB
28	—	—	—	—	—	—	—	dB
29	—	—	—	—	—	—	—	dB
30	—	—	—	—	—	—	—	dB
31	—	—	—	—	—	—	—	dB

Related Information

SPICE Models for Altera Devices
Provides the Arria V HSSI HSPICE models.

Transceiver Compliance Specification

The following table lists the physical medium attachment (PMA) specification compliance of all supported protocol for Arria V GX, GT, SX, and ST devices. For more information about the protocol parameter details and compliance specifications, contact your Altera Sales Representative.

Table 1-34: Transceiver Compliance Specification for All Supported Protocol for Arria V GX, GT, SX, and ST Devices

Protocol	Sub-protocol	Data Rate (Mbps)
PCIe	PCIe Gen1	2,500
	PCIe Gen2	5,000
	PCIe Cable	2,500
XAUI	XAUI 2135	3,125
Serial RapidIO® (SRIO)	SRIO 1250 SR	1,250
	SRIO 1250 LR	1,250
	SRIO 2500 SR	2,500
	SRIO 2500 LR	2,500
	SRIO 3125 SR	3,125
	SRIO 3125 LR	3,125
	SRIO 5000 SR	5,000
	SRIO 5000 MR	5,000
	SRIO 5000 LR	5,000
	SRIO_6250_SR	6,250
	SRIO_6250_MR	6,250
	SRIO_6250_LR	6,250

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{IN}	Input clock frequency	–3 speed grade	5	—	800[61]	MHz
		–4 speed grade	5	—	800[61]	MHz
		–5 speed grade	5	—	750[61]	MHz
		–6 speed grade	5	—	625[61]	MHz
f_{INPFD}	Integer input clock frequency to the phase frequency detector (PFD)	—	5	—	325	MHz
f_{FINPFD}	Fractional input clock frequency to the PFD	—	50	—	160	MHz
f_{VCO}[62]	PLL voltage-controlled oscillator (VCO) operating range	–3 speed grade	600	—	1600	MHz
		–4 speed grade	600	—	1600	MHz
		–5 speed grade	600	—	1600	MHz
		–6 speed grade	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	—	40	—	60	%
f_{OUT}	Output frequency for internal global or regional clock	–3 speed grade	—	—	500[63]	MHz
		–4 speed grade	—	—	500[63]	MHz
		–5 speed grade	—	—	500[63]	MHz
		–6 speed grade	—	—	400[63]	MHz

(61) This specification is limited in the Quartus Prime software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(62) The VCO frequency reported by the Quartus Prime software takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

(63) This specification is limited by the lower of the two: I/O f_{MAX} or F_{OUT} of the PLL.

HPS Clock Performance

Table 1-48: HPS Clock Performance for Arria V Devices

Symbol/Description	–I3	–C4	–C5, –I5	–C6	Unit
mpu_base_clk (microprocessor unit clock)	1050	925	800	700	MHz
main_base_clk (L3/L4 interconnect clock)	400	400	400	350	MHz
h2f_user0_clk	100	100	100	100	MHz
h2f_user1_clk	100	100	100	100	MHz
h2f_user2_clk	200	200	200	160	MHz

HPS PLL Specifications

HPS PLL VCO Frequency Range

Table 1-49: HPS PLL VCO Frequency Range for Arria V Devices

Description	Speed Grade	Minimum	Maximum	Unit
VCO range	–C5, –I5, –C6	320	1,600	MHz
	–C4	320	1,850	MHz
	–I3	320	2,100	MHz

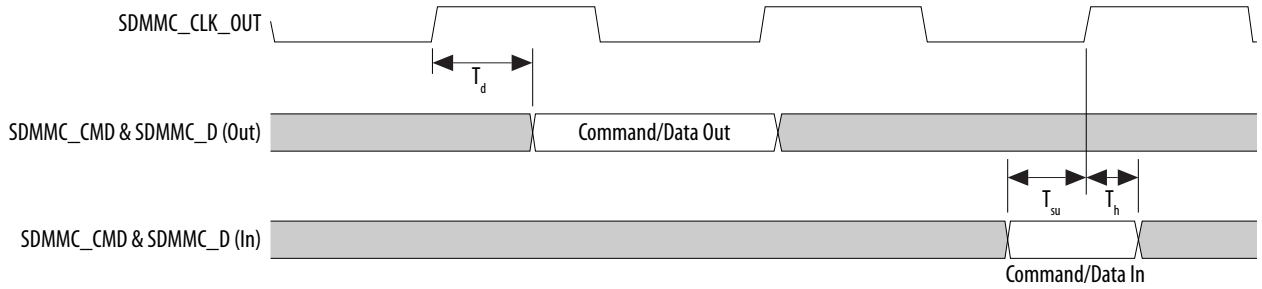
HPS PLL Input Clock Range

The HPS PLL input clock range is 10 – 50 MHz. This clock range applies to both HPS_CLK1 and HPS_CLK2 inputs.

Related Information

Clock Select, Booting and Configuration chapter
Provides more information about the clock range for different values of clock select (CSEL).

Figure 1-11: SD/MMC Timing Diagram



Related Information

Booting and Configuration Chapter, Arria V Hard Processor System Technical Reference Manual
Provides more information about CSEL pin settings in the SD/MMC Controller CSEL Pin Settings table.

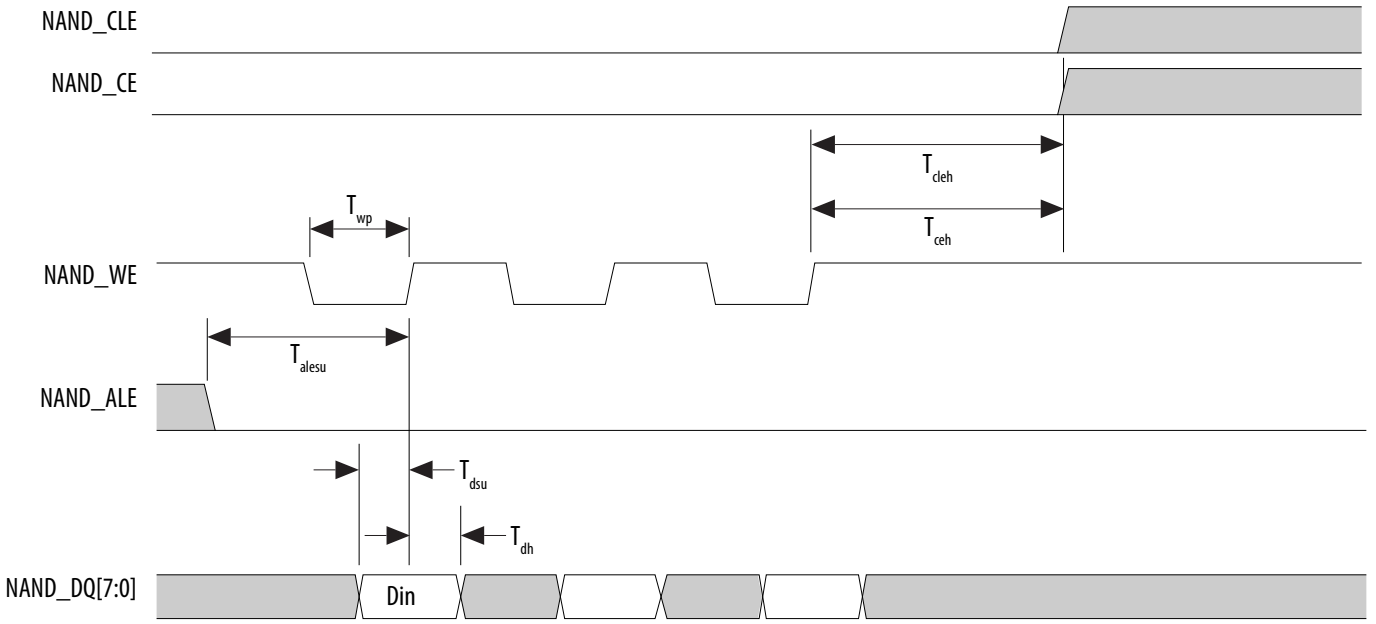
USB Timing Characteristics

PHYs that support LPM mode may not function properly with the USB controller due to a timing issue. It is recommended that designers use the MicroChip USB3300 PHY device that has been proven to be successful on the development board.

Table 1-55: USB Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk}	USB CLK clock period	—	16.67	—	ns
T_d	CLK to USB_STP/USB_DATA[7:0] output delay	4.4	—	11	ns
T_{su}	Setup time for USB_DIR/USB_NXT/USB_DATA[7:0]	2	—	—	ns
T_h	Hold time for USB_DIR/USB_NXT/USB_DATA[7:0]	1	—	—	ns

Figure 1-19: NAND Data Write Timing Diagram



Term	Definition
t_{FALL}	Signal high-to-low transition time (80–20%)
t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input
t_{OUTPJ_IO}	Period jitter on the GPIO driven by a PLL
t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL
t_{RISE}	Signal low-to-high transition time (20–80%)
Timing Unit Interval (TUI)	The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = 1/ (Receiver Input Clock Frequency Multiplication Factor) = t_C/w)
$V_{CM(DC)}$	DC common mode input voltage.
V_{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
V_{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
V_{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
$V_{IH(AC)}$	High-level AC input voltage
$V_{IH(DC)}$	High-level DC input voltage
V_{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
$V_{IL(AC)}$	Low-level AC input voltage
$V_{IL(DC)}$	Low-level DC input voltage
V_{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
V_{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission line at the transmitter.
V_{SWING}	Differential input voltage
V_X	Input differential cross point voltage

Date	Version	Changes

November 2012	3.0	• Updated Table 2, Table 4, Table 9, Table 14, Table 16, Table 17, Table 20, Table 21, Table 25, Table 29, Table 36, Table 56, Table 57, and Table 60.
		• Removed table: Transceiver Block Jitter Specifications for Arria V Devices.
		• Added HPS information:
		  • Added "HPS Specifications" section.
		  • Added Table 38, Table 39, Table 40, Table 41, Table 42, Table 43, Table 44, Table 45, Table 46, Table 47, Table 48, Table 49, and Table 50.
		  • Added Figure 7, Figure 8, Figure 9, Figure 10, Figure 11, Figure 12, Figure 13, Figure 14, Figure 15, Figure 16, Figure 17, Figure 18, and Figure 19.
		  • Updated Table 3 and Table 5.

October 2012	2.4	• Updated Arria V GX $V_{CCR\_GXBL/R}$, $V_{CCT\_GXBL/R}$, and $V_{CCL\_GXBL/R}$ minimum and maximum values, and data rate in Table 4. • Added receiver V_{ICM} (AC coupled) and V_{ICM} (DC coupled) values, and transmitter V_{OCM} (AC coupled) and V_{OCM} (DC coupled) values in Table 20 and Table 21.
August 2012	2.3	Updated the SERDES factor condition in Table 30.
July 2012	2.2	• Updated the maximum voltage for V_I (DC input voltage) in Table 1. • Updated Table 20 to include the Arria V GX -I3 speed grade. • Updated the minimum value of the fixedclk clock frequency in Table 20 and Table 21. • Updated the SERDES factor condition in Table 30. • Updated Table 50 to include the IOE programmable delay settings for the Arria V GX -I3 speed grade.
June 2012	2.1	Updated $V_{CCR\_GXBL/R}$, $V_{CCT\_GXBL/R}$, and $V_{CCL\_GXBL/R}$ values in Table 4.

Transceiver Power Supply Requirements

Table 2-7: Transceiver Power Supply Voltage Requirements for Arria V GZ Devices

Conditions	VCCR_GXB and VCCT_GXB (122)	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true: • Data rate > 10.3 Gbps. • DFE is used.	1.05	3.0	1.5	V
If ANY of the following conditions are true (123) : • ATX PLL is used. • Data rate > 6.5Gbps. • DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.	1.0			
If ALL of the following conditions are true: • ATX PLL is not used. • Data rate ≤ 6.5Gbps. • DFE, AEQ, and EyeQ are not used.	0.85	2.5		

DC Characteristics

Supply Current

Standby current is the current drawn from the respective power rails used for power budgeting.

Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.

(122) If the VCCR_GXB and VCCT_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR_GXB and VCCT_GXB are set to 0.85 V, they can be shared with the VCC core supply.

(123) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.

Symbol	Description	Conditions	Calibration Accuracy		Unit
			C3, I3L	C4, I4	
25-Ω R_S	Internal series termination with calibration (25-Ω setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%
50-Ω R_S	Internal series termination with calibration (50-Ω setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%
34-Ω and 40-Ω R_S	Internal series termination with calibration (34-Ω and 40-Ω setting)	V_{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R_S	Internal series termination with calibration (48-Ω, 60-Ω, 80-Ω, and 240-Ω setting)	V_{CCIO} = 1.2 V	±15	±15	%
50-Ω R_T	Internal parallel termination with calibration (50-Ω setting)	V_{CCIO} = 2.5, 1.8, 1.5, 1.2 V	–10 to +40	–10 to +40	%
20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω R_T	Internal parallel termination with calibration (20-Ω , 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting)	V_{CCIO} = 1.5, 1.35, 1.25 V	–10 to +40	–10 to +40	%
60-Ω and 120-Ω R_T	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V_{CCIO} = 1.2	–10 to +40	–10 to +40	%
25-Ω $R_{S\_left\_shift}$	Internal left shift series termination with calibration (25-Ω $R_{S\_left\_shift}$ setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%

Table 2-11: OCT Without Calibration Resistance Tolerance Specifications for Arria V GZ Devices

Symbol	Description	Conditions	Resistance Tolerance		Unit
			C3, I3L	C4, I4	
25-Ω R, 50-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 3.0 and 2.5 V	±40	±40	%

I/O Standard	V_{CCIO} (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V_{CCIO} + 0.3	—	0.5 × V_{CCIO}	—	0.4 × V_{CCIO}	0.5 × V_{CCIO}	0.6 × V_{CCIO}	0.3	V_{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5 × V_{CCIO} – 0.12	0.5 × V_{CCIO}	0.5 × V_{CCIO} + 0.12	0.4 × V_{CCIO}	0.5 × V_{CCIO}	0.6 × V_{CCIO}	0.44	0.44

Table 2-21: Differential I/O Standard Specifications for Arria V GZ Devices

I/O Standard	V_{CCIO} (V) (128)			V_{ID} (mV) (129)			$V_{ICM(DC)}$ (V)			V_{OD} (V) (130)			V_{OCM} (V) (130)		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
PCML	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to the "Transceiver Performance Specifications" section.														
2.5 V LVDS (131)	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.05	D_{MAX} ≤ 700 Mbps	1.8	0.247	—	0.6	1.125	1.25	1.375
						—	1.05	D_{MAX} > 700 Mbps	1.55	0.247	—	0.6	1.125	1.25	1.375
BLVDS (132)	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—	—

(128) Differential inputs are powered by VCCPD which requires 2.5 V.
(129) The minimum VID value is applicable over the entire common mode range, VCM.
(130) RL range: 90 ≤ RL ≤ 110 Ω.
(131) For optimized LVDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
(132) There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. They depend on the system topology.

Symbol	Parameter	Min	Typ	Max	Unit
t_{INCCJ} (171), (172)	Input clock cycle-to-cycle jitter (f_{REF} ≥ 100 MHz)	—	—	0.15	UI (p-p)
	Input clock cycle-to-cycle jitter (f_{REF} < 100 MHz)	-750	—	+750	ps (p-p)
t_{OUTPJ_DC} (173)	Period Jitter for dedicated clock output in integer PLL (f_{OUT} ≥ 100 MHz)	—	—	175	ps (p-p)
	Period Jitter for dedicated clock output in integer PLL (f_{OUT} < 100 Mhz)	—	—	17.5	mUI (p-p)
t_{FOUTPJ_DC} (173)	Period Jitter for dedicated clock output in fractional PLL (f_{OUT} ≥ 100 MHz)	—	—	250(176), 175(174)	ps (p-p)
	Period Jitter for dedicated clock output in fractional PLL (f_{OUT} < 100 MHz)	—	—	25(176), 17.5 (174)	mUI (p-p)
t_{OUTCCJ_DC} (173)	Cycle-to-cycle Jitter for a dedicated clock output in integer PLL (f_{OUT} ≥ 100 MHz)	—	—	175	ps (p-p)
	Cycle-to-cycle Jitter for a dedicated clock output in integer PLL (f_{OUT} < 100 MHz)	—	—	17.5	mUI (p-p)
$t_{FOUTCCJ\_DC}$ (173)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f_{OUT} ≥ 100 MHz)	—	—	250(176), 175 (174)	ps (p-p)
	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f_{OUT} < 100 MHz)	—	—	25(176), 17.5 (174)	mUI (p-p)

(171) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source with jitter < 120 ps.
(172) The f_{REF} is fIN/N specification applies when N = 1.
(173) Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.99999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in the "Worst-Case DCD on Arria V GZ I/O Pins" table.
(174) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20–0.80 must be ≥ 1200 MHz.

Description	Min	Typ	Max	Unit
Diode ideality factor	1.006	1.008	1.010	—

Periphery Performance

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.

Note: The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

High-Speed Clock Specifications

Table 2-39: High-Speed Clock Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

For LVDS applications, you must use the PLLs in integer PLL mode.

Arria V GZ devices support the following output standards using true LVDS output buffer types on all I/O banks.

- True RSDS output standard with data rates of up to 230 Mbps
- True mini-LVDS output standard with data rates of up to 340 Mbps

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
True Differential I/O Standards - f_{HSDR} (data rate)	SERDES factor J = 3 to 10 (182), (183)	(184)	—	1250	(184)	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS TX with DPA (185), (186), (187), (188)	(184)	—	1600	(184)	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(184)	—	(189)	(184)	—	(189)	Mbps
	SERDES factor J = 1, uses SDR Register	(184)	—	(189)	(184)	—	(189)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f_{HSDR} (data rate) (190)	SERDES factor J = 4 to 10 (191)	(184)	—	840	(184)	—	840	Mbps

(182) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
(183) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.
(184) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
(185) Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.
(186) Requires package skew compensation with PCB trace length.
(187) Do not mix single-ended I/O buffer within LVDS I/O bank.
(188) Chip-to-chip communication only with a maximum load of 5 pF.
(189) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
(190) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
(191) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
$t_{x\ Jitter}$ - True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	UI
$t_{x\ Jitter}$ - Emulated Differential I/O Standards with Three External Output Resistor Network	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	—	300	—	—	325	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.2	—	—	0.25	UI
t_{DUTY}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	%
t_{RISE} & t_{FALL}	True Differential I/O Standards	—	—	200	—	—	200	ps
	Emulated Differential I/O Standards with three external output resistor networks	—	—	250	—	—	300	ps
TCCS	True Differential I/O Standards	—	—	150	—	—	150	ps
	Emulated Differential I/O Standards	—	—	300	—	—	300	ps

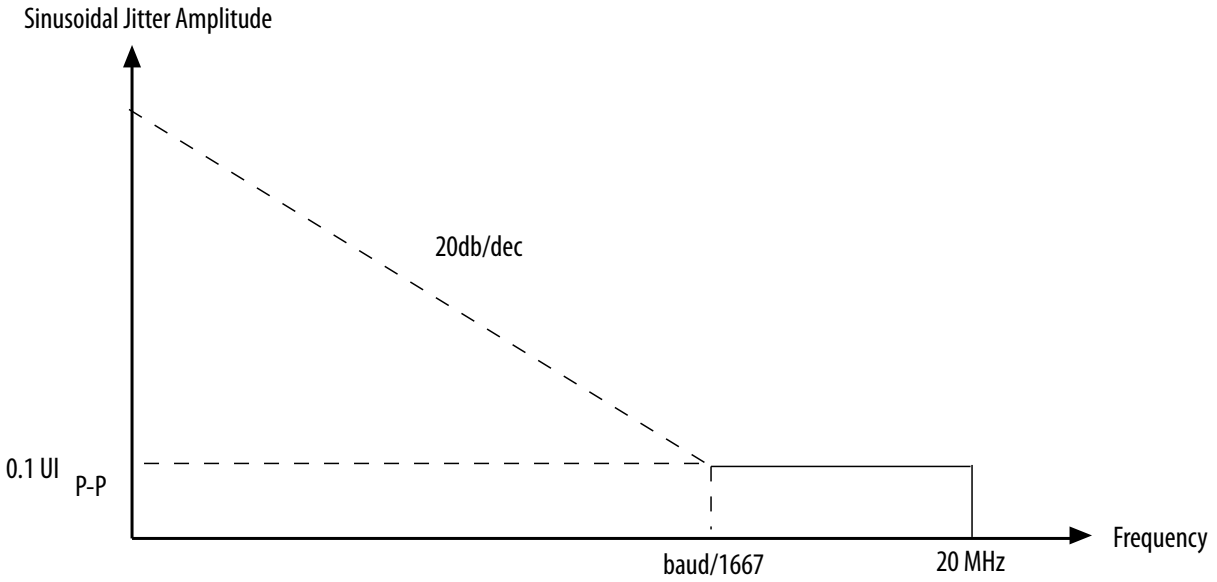
Receiver High-Speed I/O Specifications

Table 2-41: Receiver High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Figure 2-5: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps



Non DPA Mode High-Speed I/O Specifications

Table 2-46: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

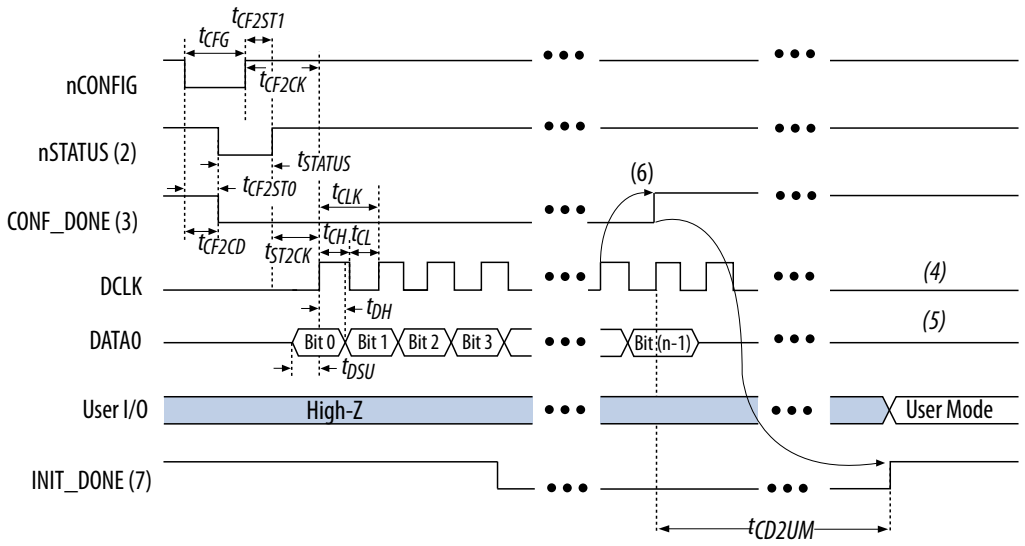
When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Sampling Window	—	—	—	300	—	—	300	ps

Passive Serial Configuration Timing

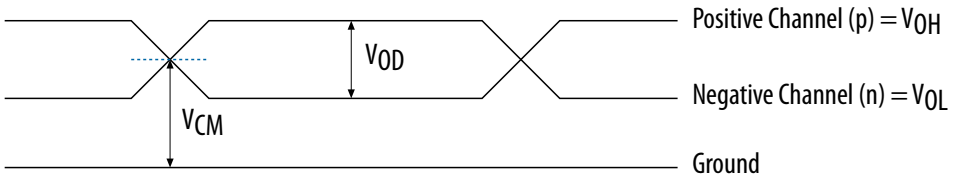
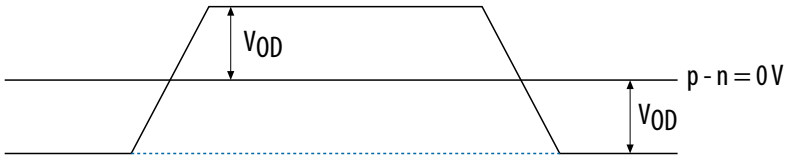
Figure 2-10: PS Configuration Timing Waveform

Timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.



Notes:

1. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
2. After power-up, the Arria V GZ device holds nSTATUS low for the time of the POR delay.
3. After power-up, before and during configuration, CONF_DONE is low.
4. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
5. DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the Device and Pins Option.
6. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF_DONE is released high after the Arria V GZ device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
7. After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Term	Definition
	Single-Ended Waveform  **Differential Waveform** 
f_{HSCLK}	Left and right PLL input clock frequency.
f_{HSDR}	High-speed I/O block—Maximum and minimum LVDS data transfer rate (f_{HSDR} = 1/TUI), non-DPA.
$f_{HSDRDPA}$	High-speed I/O block—Maximum and minimum LVDS data transfer rate ($f_{HSDRDPA}$ = 1/TUI), DPA.
J	High-speed I/O block—Deserialization factor (width of parallel data bus).